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Field Stop Trench IGBT 650 V, 75 A, TO247

AFGHL75T65SQ

Using the novel field stop 4th generation IGBT technology, AFGHL75T65SQ offers the optimum performance with both low conduction and switching losses for high efficiency operations in various applications, which does not require reverse recovery specification.

Features

- Maximum Junction Temperature: $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: $V_{CE(Sat)} = 1.6 V (Typ.) @ I_C = 75 A$
- 100% of the Parts are Tested for ILM (Note 2)
- Fast Switching
- Tight Parameter Distribution
- AEC-Q101 Qualified and PPAP Capable

Typical Applications

- Automotive
- On & Off Board Chargers
- DC-DC Converters
- PFC
- Industrial Inverter

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-to-Emitter Voltage	V _{CES}	650	V
Gate-to-Emitter Voltage Transient Gate-to-Emitter Voltage	V _{GES}	±20 ±30	V
$ \begin{array}{c} \mbox{Collector Current (Note 1)} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} \end{array} $	Ι _C	80 75	A
Pulsed Collector Current (Note 2)	I _{LM}	300	А
Pulsed Collector Current (Note 3)	I _{CM}	300	А
$ \begin{array}{ll} \mbox{Maximum Power Dissipation} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} $	P _D	375 188	W
Operating Junction / Storage Temperature Range	T _J , T _{STG}	–55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 10 seconds	TL	265	°C

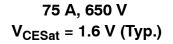
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

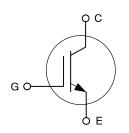
- 1. Value limited by bond wire
- 2. V_{CC} = 400 V, V_{GE} = 15 V, I_C = 300 A, R_G = 15 Ω , Inductive Load, 100% of the Parts are Tested.
- 3. Repetitive Rating: pulse width limited by max. Junction temperature



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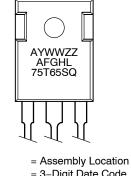
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MARKING DIAGRAM



- = 3-Digit Date Code
- ZZ AFGHL75T65SQ

A YWW

- = 2-Digit Lot Traceability Code
- = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
AFGHL75T65SQ	TO-247-3L	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.4	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

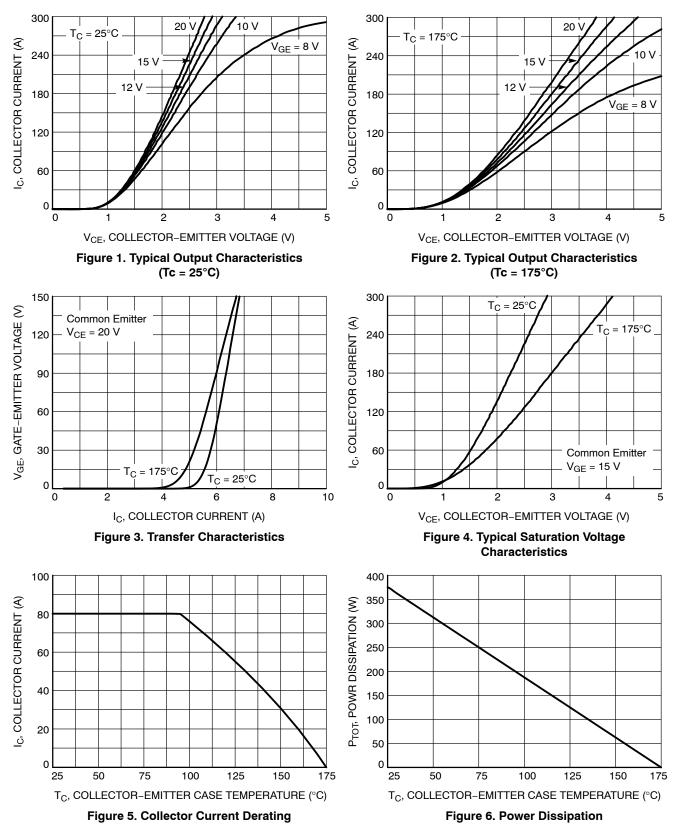
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	·					<u>.</u>
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 V,$ $I_{C} = 1 mA$	BV _{CES}	650	-	-	V
Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	_	0.6	_	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V _{GE} = 0 V, V _{CE} = 650 V	I _{CES}	_	_	250	μΑ
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	-	±400	nA
ON CHARACTERISTICS						
Gate-emitter threshold voltage	V_{GE} = V_{CE} , I_C = 75 mA	V _{GE(th)}	3.4	4.9	6.4	V
Collector-emitter saturation voltage	V_{GE} = 15 V, I _C = 75 A V _{GE} = 15 V, I _C = 75 A, T _J = 175°C	V _{CE(sat)}	-	1.6 2.0	2.1 -	V
DYNAMIC CHARACTERISTICS	•					
Input capacitance	$V_{CE} = 30 V,$	Cies	-	4574	-	pF
Output capacitance	V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	289.4	-	
Reverse transfer capacitance		C _{res}	-	11.2	-	
Gate charge total	$V_{CE} = 400 V,$	Qg	-	139	-	nC
Gate-to-emitter charge	I _C = 75 A, V _{GE} = 15 V	Q _{ge}	-	25	-	
Gate-to-collector charge		Q _{gc}	-	33	-	
SWITCHING CHARACTERISTICS, INDU	CTIVE LOAD					
Turn-on delay time	$T_{\rm C} = 25^{\circ}{\rm C},$	t _{d(on)}	-	23	-	ns
Rise time	V _{CC} = 400 V, I _C = 37.5 A,	t _r	-	17	-	
Turn-off delay time	R _G = 4.7 Ω, V _{GF} = 15 V,	t _{d(off)}	-	112	-	
Fall time	Inductive Load Energy losses include "tail" and diode	t _f	-	8	-	
Turn-on switching loss	reverse recovery. Diode from	E _{on}	-	0.61	-	mJ
Turn-off switching loss	AFGHL75T65SQD.	E _{off}	-	0.21	-]
Total switching loss		E _{ts}	-	0.82	-	
Turn-on delay time	T _C = 25°C,	t _{d(on)}	-	25	-	ns
Rise time	V _{CC} = 400 V, I _C = 75 A,	t _r	-	46	-	
Turn-off delay time	R _G = 4.7 Ω, V _{GE} = 15 V,	t _{d(off)}	-	106	-	
Fall time	Inductive Load Energy losses include "tail" and diode	t _f	-	67	-	1
Turn-on switching loss	reverse recovery. Diode from	E _{on}	-	1.86	-	mJ
Turn-off switching loss	AFGHL75T65SQD.	E _{off}	-	1.13	-	1
Total switching loss]	E _{ts}	-	2.99	-	1

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

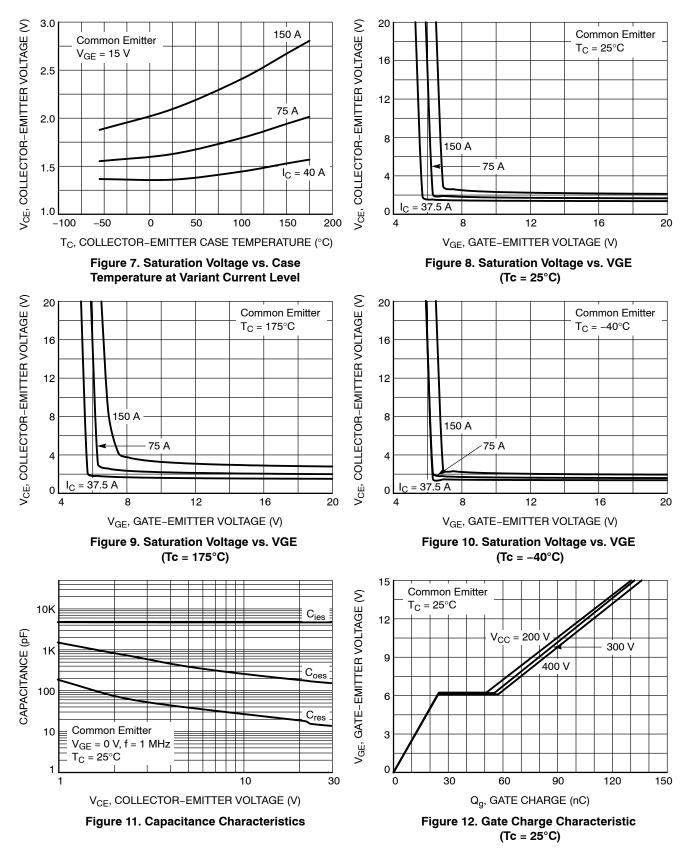
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, INDUCTIVE LOAD						
Turn-on delay time	$T_{\rm C} = 175^{\circ}{\rm C},$	t _{d(on)}	-	21	-	ns
Rise time	V _{CC} = 400 V, I _C = 37.5 A,	t _r	-	19	-	
Turn-off delay time	R _G = 4.7 Ω, V _{GF} = 15 V,	t _{d(off)}	-	126	-	
Fall time	Inductive Load Energy losses include "tail" and diode	t _f	-	7	-	
Turn-on switching loss	reverse recovery. Diode from	Eon	-	1.20	-	mJ
Turn-off switching loss	AFGHL75T65SQD.	E _{off}	-	0.41	-	
Total switching loss		E _{ts}	-	1.61	-	
Turn-on delay time	$T_{\rm C} = 175^{\circ}{\rm C},$	t _{d(on)}	-	24	-	ns
Rise time	$V_{CC} = 400 V,$ $I_{C} = 75 A,$	t _r	-	46	-	
Turn-off delay time	R _G = 4.7 Ω, V _{GF} = 15 V,	t _{d(off)}	-	115	-	
Fall time	Inductive Load Energy losses include "tail" and diode	t _f	-	72	-	
Turn-on switching loss	reverse recovery. Diode from	Eon	-	2.84	-	mJ
Turn-off switching loss	AFGHL75T65SQD.	E _{off}	-	1.35	-	1
Total switching loss		E _{ts}	-	4.20	-	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

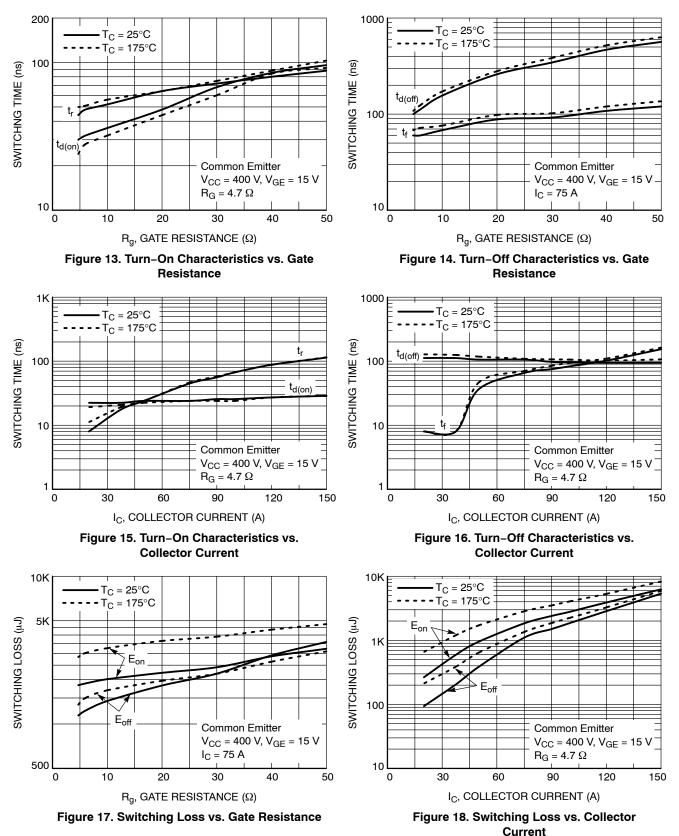
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

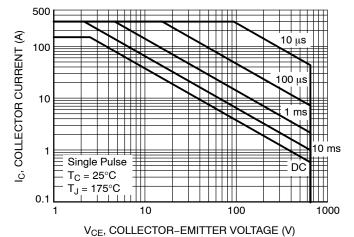


Figure 19. SOA Characteristics (FBSOA)

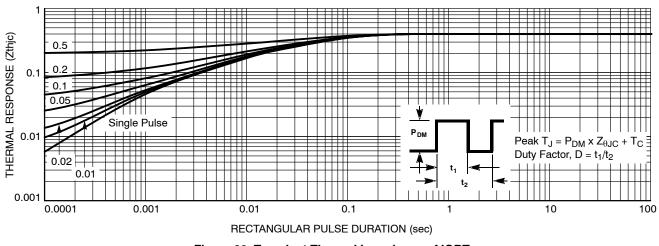
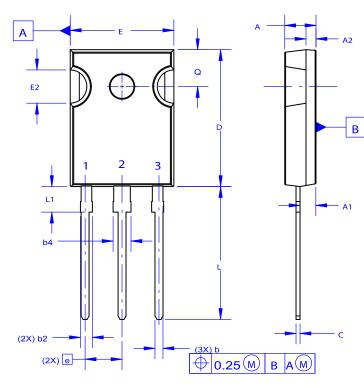


Figure 20. Transient Thermal Impedance of IGBT

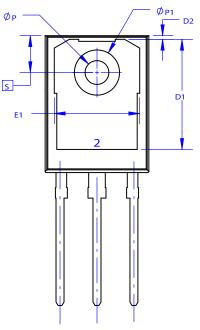
PACKAGE DIMENSIONS





NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØР	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
Ø P 1	6.60	6.80	7.00	

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